■ MN15G0804

Туре	MN15G0804		
ROM (x8-bit)	8 K		
RAM (x4-bit)	512		
Package	QFP044-P-1010E *Lead-free		
Number of Instructions	103		
Minimum Instruction Execution Time	0.96 ms at 1/4 frequency dividing (at 2.4 V to 5.5 V, 32 kHz) 1.91 ms at 1/8 frequency dividing (at 2.0 V to 5.5 V, 32 kHz)* * The lower limit for operation guarantee for EPROM built-in type is 2.3 V. VRST when using auto reset.		
Interrupts	• RESET • IRQ1 • IRQ2 • IRQ3		
Timer Counter	Timer counter 0: 8-bit × 1 (event count, pulse output) Clock source		
	Watchdog timer		
I/O Pins I/O	• Common use : 34 • Specified pull-up resistor available : 34 (software programmable) • Specified output architecture available : Nch open drain / push-pull : 34 (software programmable)		
LCD	30 segments × 4 commons (1/2, 1/3, 1/4 duty)		
Remote Control Output	Duty and period are variable.		
Notes	Auto reset circuit selectable (mask option)		

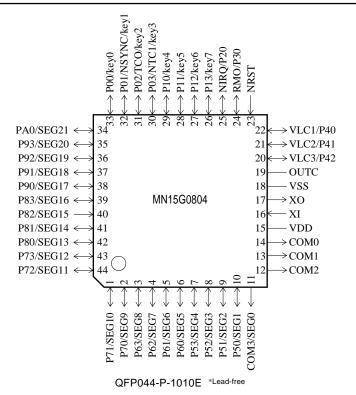
Electrical Characteristics

Supply current

Parameter	Symbol	Condition	Limit			Unit
			min	typ	max	Onit
	IDD1	fxi = 32.768 kHz (1/8 dividing) when using multiply circuit		3.0	5.0	mA
Operating supply current	IDD2	fxi = 32.768 kHz (1/8 dividing)		10	40	μА
Supply current at HALT	IDD3	fxi = 32.768 kHz (1/8 dividing)		3	15	mA
Supply current at STOP	IDD6	fxi = 32.768 kHz		2.0	5.0	μА
	IDD7	fxi = Stop		1.0	3.5	μA
Auto reset power cunsumption	IDD9			3.0	6.0	μА

 $(Ta = -10^{\circ}C \text{ to } +60^{\circ}C, VDD = 3.0 \text{ V}, VSS = 0 \text{ V})$

Pin Assignment



Support Tool

In-circuit Emulator	PX-ICE1500 + PX-PRB15G1604-QFP044-P-1010E		
EPROM Built-in Type	Туре	MN15GP1604	
	ROM (× 8-bit)	16 K	
	RAM (× 4-bit)	512	
	Minimum instruction execution time	0.96 μs at 1/4 frequency dividing (at 2.4 V to 5.5 V, 32 kHz)	
		$1.91\;\mu s$ at 1/8 frequency dividing (at 2.3 V to 5.5 V, 32 kHz)	
	Package	QFP044-P-1010E *Lead-free	

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